SP225GN

(UL ANSI: NO ANSI) Hi-Tg, Halogen-free, No-flow Prepreg

FEATURES

- Excellent mechanical process ability, and available for punching.
- Improve warpage performance of rigid-flex PCB.

APPLICATIONS

Suitable for bonding used in heat sink board, die cavity board and multilayer rigid-flex PCB applications.

GENERAL PROPERTIES

Test Items	Test Condition	Test Method	Unit	Typical Value
Tg	TMA	2.4.25	℃	190
	DMA	2.4.24.2		225
Peel Strength	Copper Foil (1/3oz)	2.4.8	N/mm	0.7
	Copper Foil (1/2oz)	2.4.8		1.0
	CVL	2.4.9		1.0
T300	TMA	2.4.24.1	min	>30
Td	TGA (5% wt. loss)	2.4.24.6	℃	410
Thermal Stress	288℃, solder dip	-	s	>600
Water Absorption	E-1/105+D-24/23	2.6.2.1	%	0.15
CTE Z-axis: Before Tg	TMA	2.4.24	PPM/℃	34
CTE Z-axis: After Tg	TMA	2.4.24		115
Dielectric Constant (RC67%@1GHz)	C-24/23/50	2.5.5.9	-	4.21
Dissipation Factor (RC67%@1GHz)	C-24/23/50	2.5.5.9	-	0.015
Flammability	-	UL94	-	V-0

Remarks: Specimen thickness: 0.8mm. All typical value listed above is for your reference only, please turn to Shengyi Technology Co., Ltd. for detailed information.

Explanations: C=Humidity conditioning; D=Immersion conditioning in distilled water; E=temperature conditioning.

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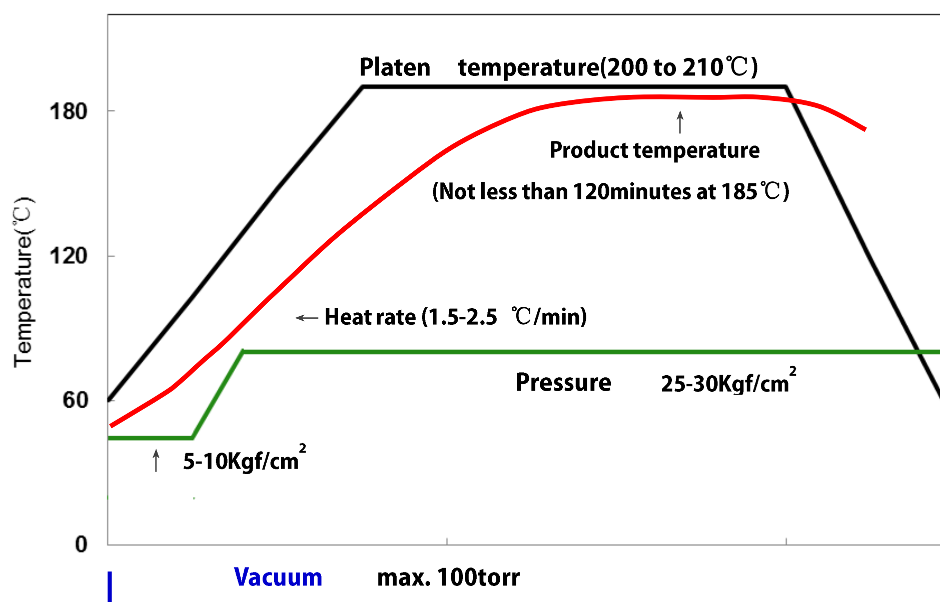
PURCHASING INFORMATION

Specification	Resin Content (%)	Resin Flow (mm)	Cured Thickness (μm)
1086	71	≤0.5	100
1078	71	≤0.5	90
1078	67	≤0.5	80
1078	64	≤0.5	70
1067	71	≤0.5	60
1067	66	≤0.5	50
1037	68	≤0.5	40
1027	64	≤0.5	30
1027	57	≤0.5	25

Remarks: Available in roll size or panel form.

HOT PRESSING CYCLE



Heat Rate: 1.5-2.5℃/min (80-140℃)

Apply Full Pressure at 80-110℃

Kiss Pressure: 5-10kgf/cm^2

Curing Temperature: ≥185℃

Full Pressure: 25-30kgf/cm^2

Curing Time: ≥120min